

Abstract of the Disclosure:

A method for removing structures from a substrate is described. The method includes providing a substrate that has the structures that must be removed, applying a sacrifice 5 layer, and removing the structures and the sacrifice layer in a polishing step. The method has the advantage that the sacrifice layer surrounds the structures that must be removed and stabilizes them, so that the structures can be eroded slowly and successively in the subsequent polishing step without breaking off. This prevents a smearing of the material of the structures such as occurs given direct polishing without a sacrifice layer.

REL/tk